

BUDGET SENSITIVE MANUAL DIE BONDER

# T-4909

The **T-4909** is a manual, high quality die bonder with superior ergonomic design. As with all of Tresky's products, the **T-4909** incorporates True Vertical Technology™ which guarantees parallelism between chip and substrate at any bond height.

**T-4909** Application Packages:

- Epoxy
- Eutectic
- Ultrasonic
- Flip-Chip

Force controlled

True Vertical Technology™

Easy to use

MICRO ASSEMBLY

T-4909



# TRESKY

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Excellent performance, ergonomically designed and high reliability makes the T-4909 ideal for small and medium volume production.

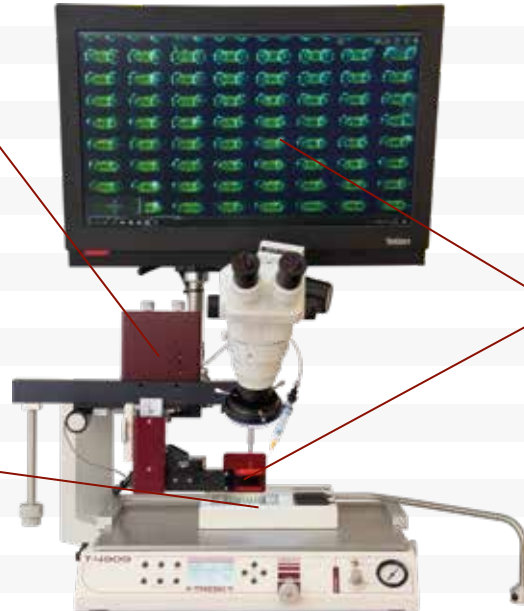
#### APPLICATIONS

Die Attach, Flip-Chip, MEMS, MOEMS, VCSEL, Ultrasonic, RFID, Adhesive Bonding, Eutectic Bonding, .....

#### FEATURES AND OPTIONS

- TRUE VERTICAL TECHNOLOGY™  
Z-movement 60mm with 360° Tool rotation; Dispenser, Stamping, Scrub, Ultrasonic, Tool Heating, Pre Form Spindle, ...

- XY air-cushioned placement stage with micrometer control, supporting: Waffle - / Gel - Pack -, Substrate - Holder, various Heating Plates.



- Flip-Chip Ultra (Ultra HD image with Beam Splitter)

#### TECHNICAL DATA

XY- Movement (placement stage):	180mm x 180mm (manual)
Z- Movement:	60mm (manual)
Spindle Rotation:	360°
Placement accuracy:	±10µm; ±5µm optional (process depending)
Connections:	Compressed air 5 - 6 bar / Vacuum 0.6 bar (abs)
Dimensions:	755mm x 730mm x 500mm
Weight:	30kg
Voltage:	110V / 220V

Note: All specifications are subject to change without notice

#### Represented by

#### Headquarters

[www.tresky.com](http://www.tresky.com)

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